ON Semiconductor

Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,



LCD and Camera EMI Filter Array with ESD Protection

CM1430

Features

- Four, six and eight channels of EMI filtering with integrated ESD protection
- Pi-style EMI filters in a capacitor-resistorcapacitor (C-R-C) network
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Greater than 20dB attenuation (typical) at 1 GHz
- TDFN package with 0.40mm lead pitch:
 - 4-ch. = 8-lead TDFN
 - 6-ch. = 12-lead TDFN
 - 8-ch. = 16-lead TDFN
- Tiny TDFN package size:
 - 8-lead: 1.7mm x 1.35mm
 - 12-lead: 2.5mm x 1.35mm
 - 16-lead: 3.3mm x 1.35mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free version available

Applications

- LCD and Camera data lines in mobile handsets.
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- Wireless handsets
- Handheld PCs/PDAs
- · LCD and camera modules

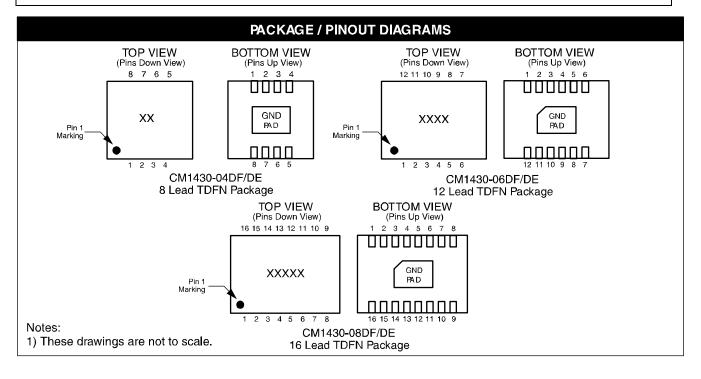
Product Description

The CM1430 is a family of pi-style EMI filter arrays with ESD protection, which integrates four, six and eight filters (C-R-C) in small form factor TDFN 0.40mm pitch packages. The CM1430 has component values of 8.5pF-100 Ω -8.5pF per channel. The CM1430 has a cut-off frequency of 200MHz and can be used in applications with data rates up to 80Mbps. The parts include ESD diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD protection diodes safely dissipate ESD strikes of ±15kV, well beyond the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30kV.

These devices are particularly well-suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of their small package and easy-to-use pin assignments. In particular, the CM1430 is ideal for EMI filtering and protecting data and control lines for the I/O data ports, LCD display and camera interface in mobile handsets.

The CM1430 is housed in space-saving, low-profile 8-,12- and 16-lead TDFN packages with a 0.4mm pitch and is available with lead-free finishing. This new small TDFN package provides up to 42% board space savings vs. the 0.50mm pitch TDFN packages.

FILTER+ESDn* GND 1 of 4, 6 or 8 EMI/RFI Filter Channels with Integrated ESD Protection



PIN DESCRIPTIONS										
DE	DEVICE PIN(s)					DEVICE PIN(s)		DEVICE PIN(s)		
-04	-06	-08	NAME	DESCRIPTION		-04	-06	-08	NAME	DESCRIPTION
1	1	1	FILTER1	Filter + ESD Channel 1		8	12	16	FILTER1	Filter + ESD Channel 1
2	2	2	FILTER2	Filter + ESD Channel 2		7	11	15	FILTER2	Filter + ESD Channel 2
3	3	3	FILTER3	Filter + ESD Channel 3		6	10	14	FILTER3	Filter + ESD Channel 3
4	4	4	FILTER4	Filter + ESD Channel 4		5	9	13	FILTER4	Filter + ESD Channel 4
	5	5	FILTER5	Filter + ESD Channel 5			8	12	FILTER5	Filter + ESD Channel 5
	6	6	FILTER6	Filter + ESD Channel 6			7	11	FILTER6	Filter + ESD Channel 6
		7	FILTER7	Filter + ESD Channel 7				10	FILTER7	Filter + ESD Channel 7
		8	FILTER8	Filter + ESD Channel 8				9	FILTER8	Filter + ESD Channel 8
(SND PA	ΔD	GND	Device Ground						

Ordering Information

PART NUMBERING INFORMATION									
		Standard Finish Lead-free Finish							
Pins	Package	Ordering Part Number¹	Part Marking	Ordering Part Number¹	Part Marking				
8	TDFN-8	CM1430-04DF	VF	CM1430-04DE	VE				
12	TDFN-12	CM1430-06DF	N30F	CM1430-06DE	N30E				
16	TDFN-16	CM1430-08DF	N308F	CM1430-08DE	N308E				

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	RATING	UNITS						
Storage Temperature Range	-65 to +150	°C						
DC Power per Resistor	100	mW						
DC Package Power Rating	500	mW						

STANDARD OPERATING CONDITIONS							
PARAMETER	RATING	UNITS					
Operating Temperature Range	-40 to +85	°C					

	ELECTRICAL OPERATIN	G CHARACTERIS	STICS	(SEE NOTE	1)	
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
R	Resistance		80	100	120	Ω
C _{TOTAL}	Total Channel Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	14	17	22	pF
С	Capacitance C1	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	7	8.5	11	pF
V _{DIODE}	Standoff Voltage	I _{DIODE} =10μA		6.0		٧
I _{LEAK}	Diode Leakage Current (reverse bias)	V _{DIODE} =+3.3V		0.1	1.0	μА
V _{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	$I_{LOAD} = 10mA$ $I_{LOAD} = -10mA$	5.6 -1.5	6.8 -0.8	9.0 -0.4	V V
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	Note 2	30 15			kV kV
R _{DYN}	Dynamic Resistance Positive Negative			2.3 0.9		Ω
f _c	Cut-off Frequency Z_{SOURCE} =50 Ω , Z_{LOAD} =50 Ω	Channel R = 100Ω , Channel C = 8.5 pF		200		MHz

Note 1: T_A =25°C unless otherwise specified. Note 2: ESD applied to input and output pins with respect to GND, one at a time.

Performance Information

Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

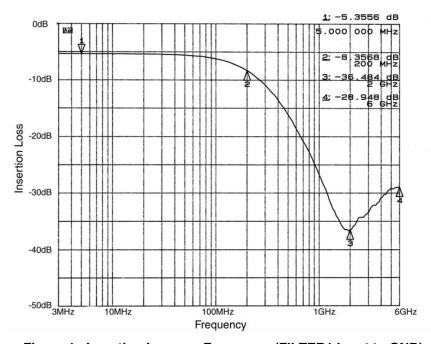


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND)

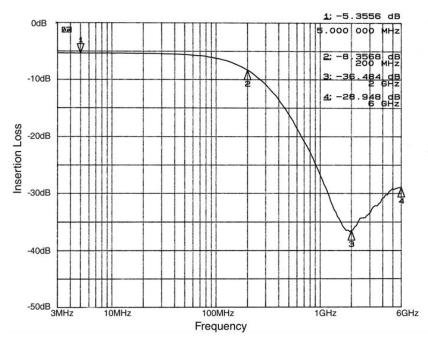


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND)

Performance Information (cont'd)

Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

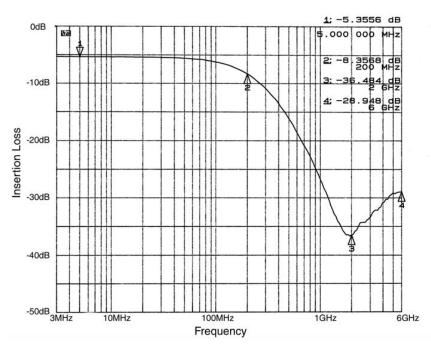


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND)

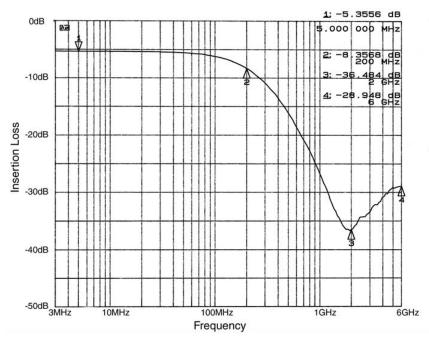


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND)

Performance Information (cont'd)

Typical Diode Capacitance vs. Input Voltage

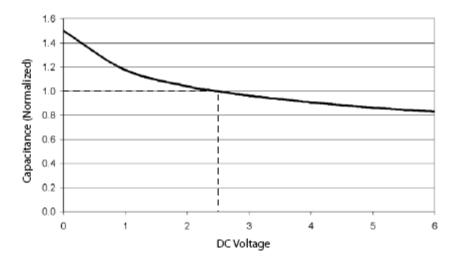


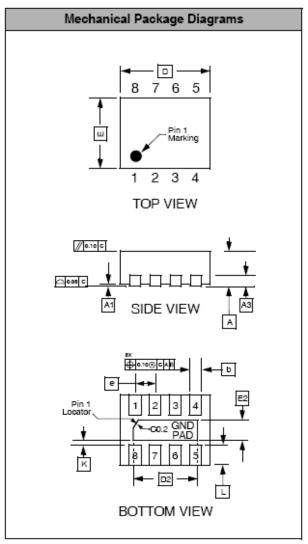
Figure 5. Filter Capacitance vs. Input Voltage (normalized to capacitance at 2.5VDC and 25°C)

Mechanical Details

CM1430-04DF/DE Mechanical Specifications

Dimensions for the CM1430-04DF/DE suplied in a 8-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-8, see the California Micro Devices TDFN Package Information document.

	PAC	KAGE	DIME	NSIO	NS				
Package		TDFN							
JEDEC No.		MO-229C							
Leads				8					
Dim.	N	lillimete	rs		Inches				
Biiii.	Min	Nom	Max	Min	Nom	Max			
Α	0.70	0.75	0.80	0.028	0.030	0.031			
A 1	0.00	0.02	0.05	0.000	0.001	0.002			
А3		0.20 RE	F	C).008 REF				
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	1.60	1.70	1.80	0.063	0.067	0.071			
D2	1.10	1.20	1.30	0.043	0.047	0.051			
E	1.25	1.35	1.45	0.049	0.053	0.057			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	С	C	.016 BS	C			
К	0.20			0.008					
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel			3000	pieces					
	Contro	olling din	nension:	millime	ters				



Dimensions for 8-Lead, 0.4mm pitch TDFN package

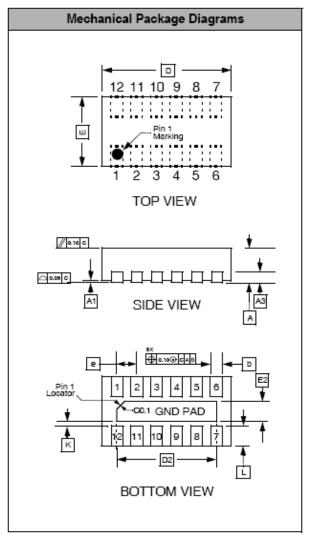
This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Mechanical Details (cont'd)

CM1430-06DF/DE Mechanical Specifications

Dimensions for the CM1430-06DF/DE suplied in a 12-lead, 0.4mm pitch TDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS				
Package	TDFN								
JEDEC No.	MO-229C								
Leads			1	12					
Dim.	M	lillimete	rs		Inches				
Biiii.	Min	Nom	Max	Min	Nom	Max			
Α	0.70	0.75	0.80	0.028	0.030	0.031			
A1	0.00	0.02	0.05	0.000	0.001	0.002			
А3	(0.20 RE	F	C	0.008 REF				
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	2.40	2.50	2.60	0.094	0.098	0.102			
D2	1.90	2.00	2.10	0.075	0.079	0.083			
E	1.25	1.35	1.45	0.049	0.053	0.057			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	С	C	.016 BS	Ö			
κ	0.20			0.008					
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel			3000	0 pieces					
	Contro	olling din	nension:	millime	ters				



Dimensions for 12-Lead, 0.4mm pitch TDFN package

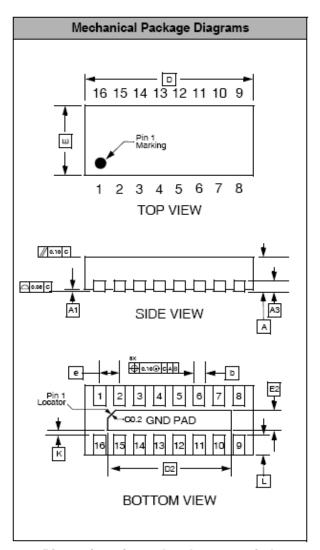
This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Mechanical Details (cont'd)

CM1430-08DF/DE Mechanical Specifications

Dimensions for the CM1430-08DF/DE supplied in a 16-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-16, see the California Micro Devices TDFN Package Information document.

	PAC	KAGE	DIME	NSIO	NS				
Package	ckage TDFN								
JEDEC No.	MO-229C								
Leads			1	16					
Dim.	N	lillimete	rs		Inches				
Diiii.	Min	Nom	Max	Min	Nom	Max			
Α	0.70	0.75	0.80	0.028	0.030	0.031			
A 1	0.00	0.02	0.05	0.000	0.001	0.002			
А3	C	.200 RE	F	C).008 REF				
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	3.20	3.30	3.40	0.126	0.130	0.134			
D2	2.70	2.80	2.90	0.106	0.110	0.114			
E	1.25	1.35	1.45	0.049	0.053	0.057			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	С	C	.016 BS	Ö			
К	0.20			0.008					
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel			3000	pieces					
	Contro	olling din	nension:	millimet	ters				



Dimensions for 16-Lead, 0.4mm pitch TDFN package

This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

CM1430

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LI TERATURE FULFI LLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, M ddle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semi conduct or Website: www.onsemi.com Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative